Board Stack Report

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Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste	•		
2 .		Top Overlay			
3		Top Solder	Solder Resist	0.025mm	3.5
4		Top Layer	Copper	0.035mm	
5		Dielectric 1	FR-4	0.350mm	4.3
6		Internal Plane 1	Copper	0.018mm	
7		Dielectric 3		0.710mm	4.3
8		Internal Plane 2	Copper	0.018mm	
9		Dielectric 2		0.350mm	4.3
10		Bottom Layer	Copper	0.035mm	
11		Bottom Solder	Solder Resist	0.025mm	3.5
12 "		Bottom Overlay			
13		Bottom Paste			

Height: 1.567mm